

Power MOSFET

TO-220AB


N-Channel MOSFET

FEATURES

- Low gate charge Q_g results in simple drive requirement
- Improved gate, avalanche, and dynamic dV/dt ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Effective C_{oss} specified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


 Available
RoHS*
 Available

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptable power supply
- High speed power switching

TYPICAL SMPS TOPOLOGIES

- Two transistor forward
- Half bridge
- Full bridge

PRODUCT SUMMARY

| | | |
|---------------------------|------------------------|------|
| V_{DS} (V) | 500 | |
| $R_{DS(on)}$ (Ω) | $V_{GS} = 10\text{ V}$ | 0.85 |
| Q_g max. (nC) | 38 | |
| Q_{gs} (nC) | 9.0 | |
| Q_{gd} (nC) | 18 | |
| Configuration | Single | |

ORDERING INFORMATION

| | |
|---------------------------------|----------------|
| Package | TO-220AB |
| Lead (Pb)-free | IRF840APbF |
| Lead (Pb)-free and halogen-free | IRF840APbF-BE3 |

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)


| PARAMETER | SYMBOL | LIMIT | UNIT | |
|---|----------------------------------|-----------------------------------|---------------------|------------------|
| Drain-source voltage | V_{DS} | 500 | V | |
| Gate-source voltage | V_{GS} | ± 30 | | |
| Continuous drain current | V_{GS} at 10 V | $T_C = 25\text{ }^\circ\text{C}$ | A | |
| | | $T_C = 100\text{ }^\circ\text{C}$ | | 5.1 |
| Pulsed drain current ^a | I_{DM} | 32 | | |
| Linear derating factor | | 1.0 | W/ $^\circ\text{C}$ | |
| Single pulse avalanche energy ^b | E_{AS} | 510 | mJ | |
| Repetitive avalanche current ^a | I_{AR} | 8.0 | A | |
| Repetitive avalanche energy ^a | E_{AR} | 13 | mJ | |
| Maximum power dissipation | $T_C = 25\text{ }^\circ\text{C}$ | P_D | 125 | W |
| Peak diode recovery dV/dt ^c | | dV/dt | 5.0 | V/ns |
| Operating junction and storage temperature range | | T_J, T_{stg} | -55 to +150 | $^\circ\text{C}$ |
| Soldering recommendations (peak temperature) ^d | For 10 s | | 300 | |
| Mounting torque | 6-32 or M3 screw | | 10 | |
| | | | 1.1 | N · m |

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- $V_{DD} = 50\text{ V}$, starting $T_J = 25\text{ }^\circ\text{C}$, $L = 16\text{ mH}$, $R_g = 25\text{ }\Omega$, $I_{AS} = 8.0\text{ A}$ (see fig. 12)
- $I_{SD} \leq 8.0\text{ A}$, $dI/dt \leq 100\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^\circ\text{C}$
- 1.6 mm from case



| THERMAL RESISTANCE RATINGS | | | | |
|-------------------------------------|------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum junction-to-ambient | R_{thJA} | - | 62 | °C/W |
| Case-to-sink, flat, greased surface | R_{thCS} | 0.50 | - | |
| Maximum junction-to-case (drain) | R_{thJC} | - | 1.0 | |

| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | | |
|---|-----------------------|---|---|------|------|-----------|---------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-source breakdown voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | | 500 | - | - | V |
| V_{DS} temperature coefficient | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$ | | - | 0.58 | - | V/°C |
| Gate-source threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | | 2.0 | - | 4.0 | V |
| Gate-source leakage | I_{GSS} | $V_{GS} = \pm 30\text{ V}$ | | - | - | ± 100 | nA |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$ | | - | - | 25 | μA |
| | | $V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$ | | - | - | 250 | |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}$ | $I_D = 4.8\text{ A}^b$ | - | - | 0.85 | Ω |
| Forward transconductance | g_{fs} | $V_{DS} = 50\text{ V}, I_D = 4.8\text{ A}^b$ | | 3.7 | - | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$, see fig. 5 | | - | 1018 | - | pF |
| Output capacitance | C_{oss} | | | - | 155 | - | |
| Reverse transfer capacitance | C_{riss} | | | - | 8.0 | - | |
| Output capacitance | C_{oss} | $V_{GS} = 0\text{ V}; V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$ | | - | 1490 | - | |
| Output capacitance | C_{oss} | $V_{GS} = 0\text{ V}; V_{DS} = 400\text{ V}, f = 1.0\text{ MHz}$ | | - | 42 | - | |
| Effective output capacitance | $C_{oss\text{ eff.}}$ | $V_{GS} = 0\text{ V}; V_{DS} = 0\text{ V to } 400\text{ V}^c$ | | - | 56 | - | |
| Total gate charge | Q_g | $V_{GS} = 10\text{ V}$ | $I_D = 8\text{ A}, V_{DS} = 400\text{ V}$, see fig. 6 and 13 ^b | - | - | 38 | nC |
| Gate-source charge | Q_{gs} | | | - | - | 9.0 | |
| Gate-drain charge | Q_{gd} | | | - | - | 18 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD} = 250\text{ V}, I_D = 8\text{ A}$ $R_g = 9.1\text{ }\Omega, R_D = 31\text{ }\Omega$, see fig. 10 ^b | | - | 11 | - | ns |
| Rise time | t_r | | | - | 23 | - | |
| Turn-off delay time | $t_{d(off)}$ | | | - | 26 | - | |
| Fall time | t_f | | | - | 19 | - | |
| Gate input resistance | R_g | $f = 1\text{ MHz}$, open drain | | 0.7 | - | 3.7 | Ω |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous source-drain diode current | I_S | MOSFET symbol showing the integral reverse p - n junction diode |  | - | - | 8.0 | A |
| Pulsed diode forward current ^a | I_{SM} | | | - | - | 32 | |
| Body diode voltage | V_{SD} | $T_J = 25\text{ }^\circ\text{C}, I_S = 8\text{ A}, V_{GS} = 0\text{ V}^b$ | | - | - | 2.0 | V |
| Body diode reverse recovery time | t_{rr} | $T_J = 25\text{ }^\circ\text{C}, I_F = 8\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$ | | - | 422 | 633 | ns |
| Body diode reverse recovery charge | Q_{rr} | | | - | 2.16 | 3.24 | μC |
| Forward turn-on time | t_{on} | Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D) | | | | | |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$
- c. $C_{oss\text{ eff.}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

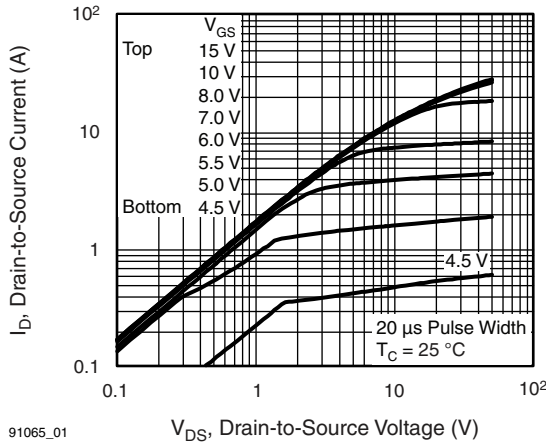


Fig. 1 - Typical Output Characteristics, $T_C = 25^\circ\text{C}$

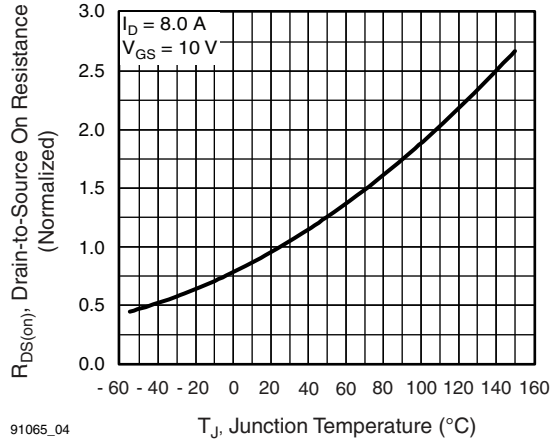


Fig. 4 - Normalized On-Resistance vs. Temperature

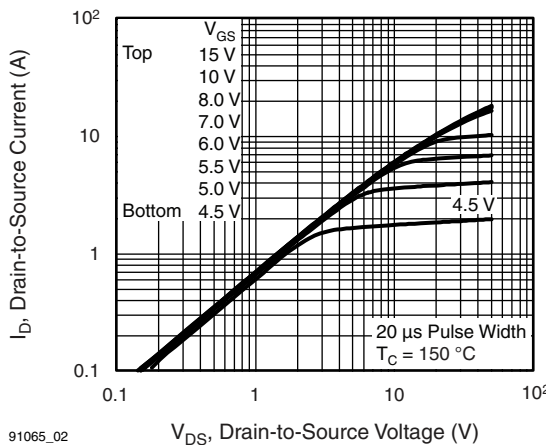


Fig. 2 - Typical Output Characteristics, $T_C = 150^\circ\text{C}$

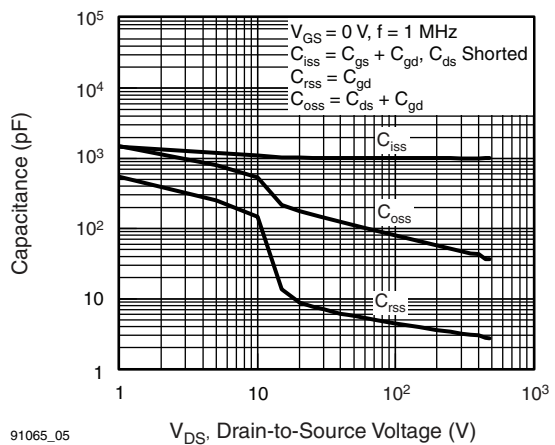


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

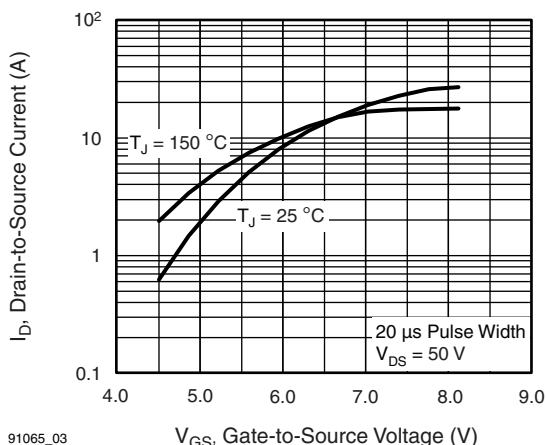


Fig. 3 - Typical Transfer Characteristics

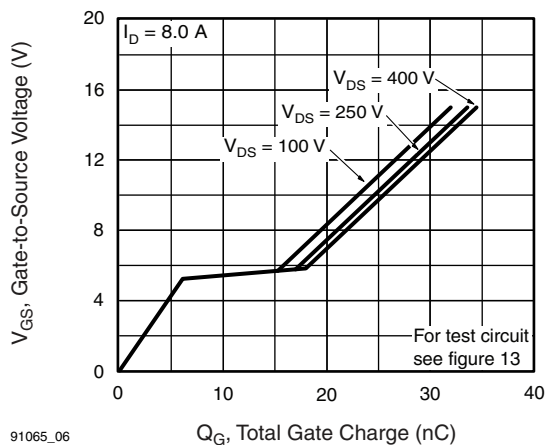


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

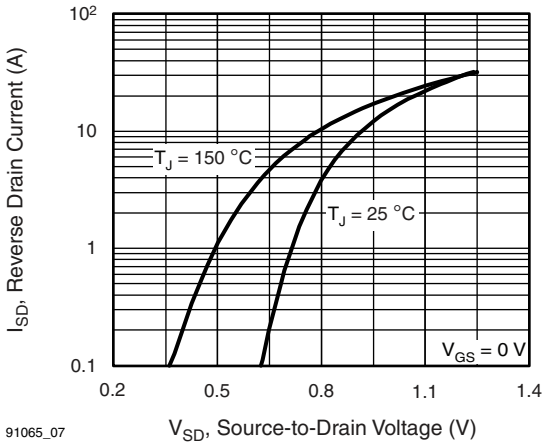


Fig. 7 - Typical Source-Drain Diode Forward Voltage

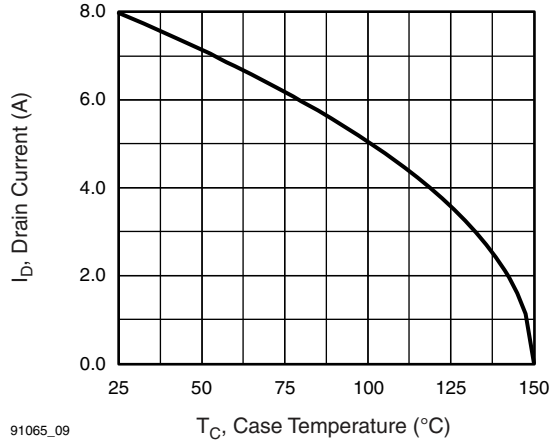


Fig. 9 - Maximum Drain Current vs. Case Temperature

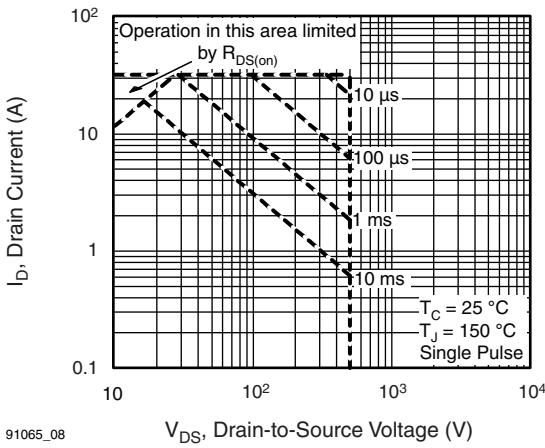


Fig. 8 - Maximum Safe Operating Area

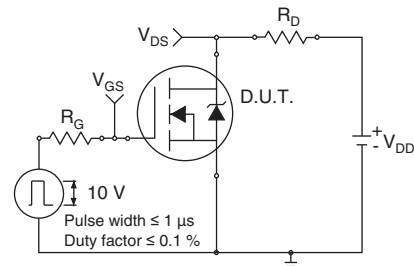


Fig. 10a - Switching Time Test Circuit

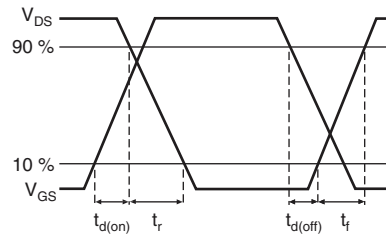


Fig. 10b - Switching Time Waveforms

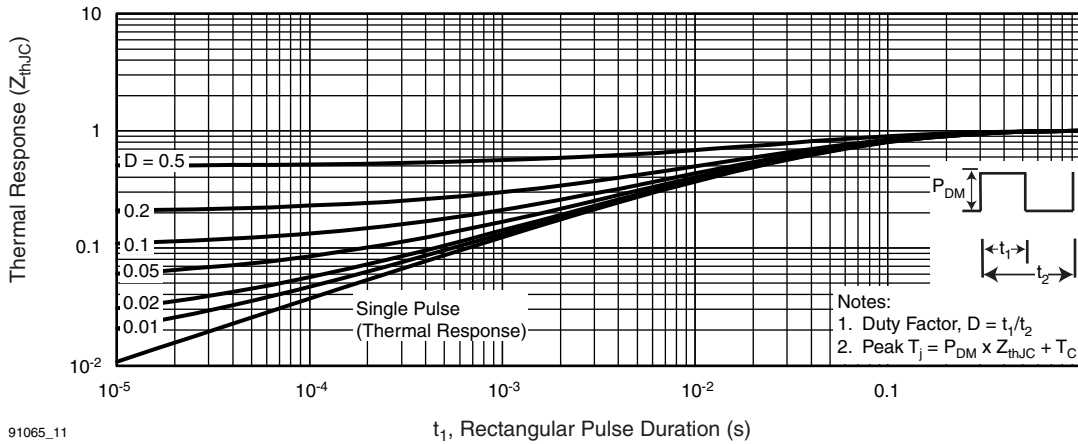


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

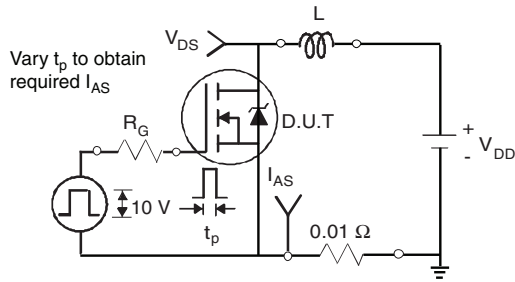


Fig. 12a - Unclamped Inductive Test Circuit

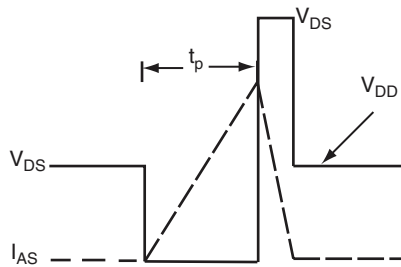
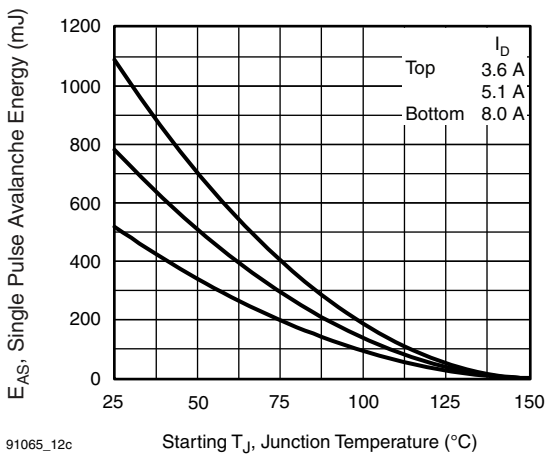


Fig. 12b - Unclamped Inductive Waveforms



91065_12c

Fig. 12c - Maximum Avalanche Energy vs. Drain Current

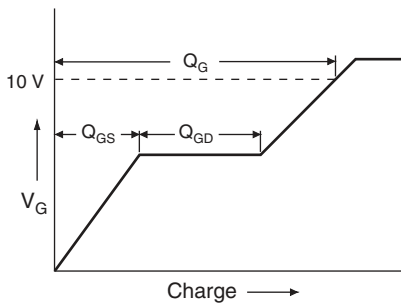
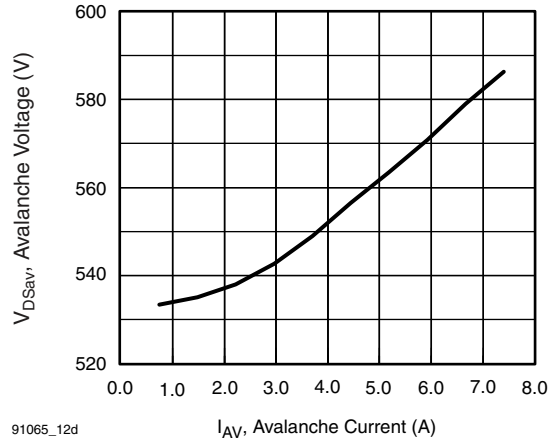


Fig. 12d - Basic Gate Charge Waveform



91065_12d

Fig. 13a - Typical Drain-to-Source Voltage vs. Avalanche Current

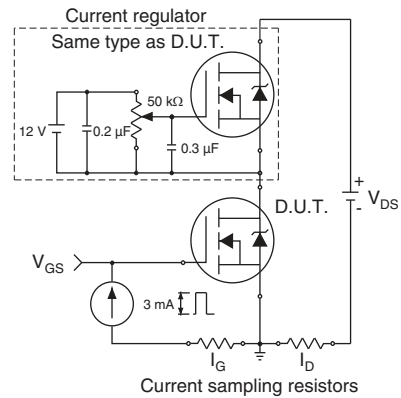
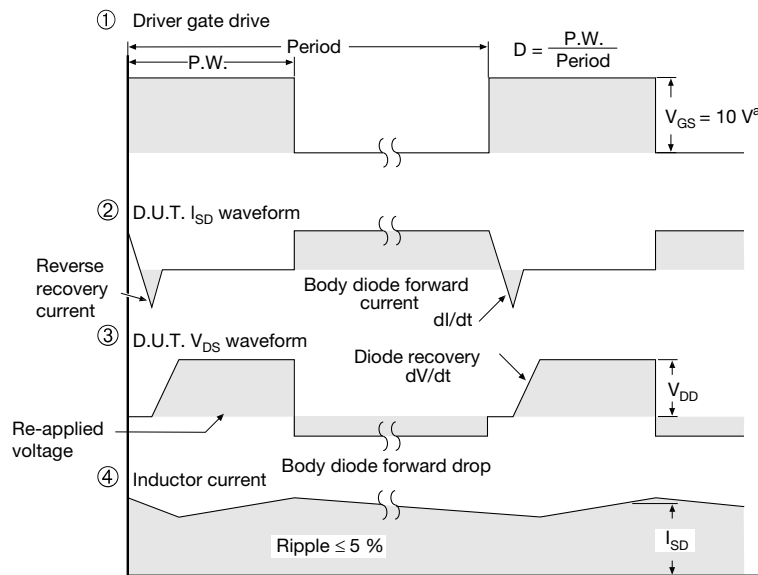
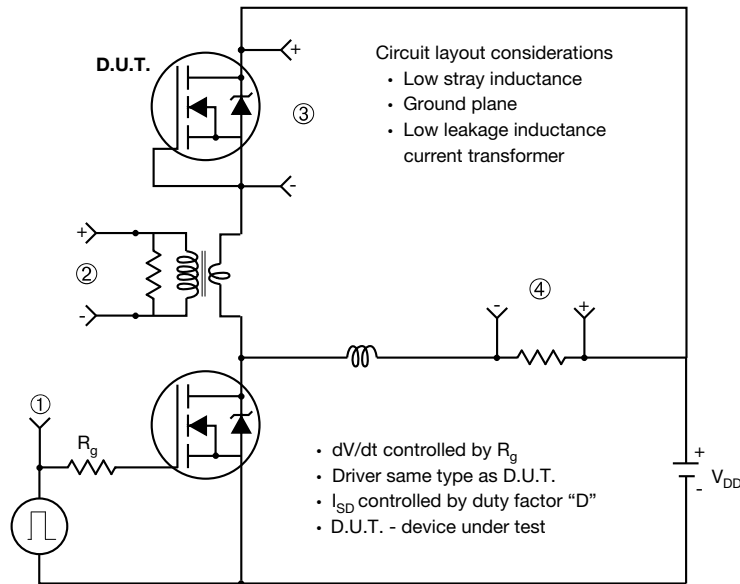


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

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TO-220-1



| DIM. | MILLIMETERS | | INCHES | |
|------|-------------|-------|--------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.24 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.02 | 0.027 | 0.040 |
| b(1) | 1.14 | 1.78 | 0.045 | 0.070 |
| c | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.33 | 15.85 | 0.564 | 0.624 |
| E | 9.96 | 10.52 | 0.392 | 0.414 |
| e | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.10 | 6.71 | 0.240 | 0.264 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.36 | 14.40 | 0.526 | 0.567 |
| L(1) | 3.33 | 4.04 | 0.131 | 0.159 |
| Ø P | 3.53 | 3.94 | 0.139 | 0.155 |
| Q | 2.54 | 3.00 | 0.100 | 0.118 |

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DWG: 6031

Note

- M* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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